

BOARD CHARACTERISTICS

Copper Layer Count:	4	Board Thickness:	62 mils
Board overall dimensions:	3550.00 mils x 3982.07 mils		
Min track/spacing:	8.00 mils / 8.00 mils	Min hole diameter:	7.87 mils
Copper Finish:	ENIG	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	Yes, bevelled 30deg minimum.		

FAB NOTES:

1. IPC-6012E Class 2
2. Matte Green soldermask, White silkscreen.
3. Fabricate on SH260
4. 1oz outer, 1oz inner copper.
5. Bevel edge connector 30 degrees minimum.
6. Board target thickness shall be 0.062"
7. Immersion gold plating on finger thickness shall be 2U"

FAB COMMENTS:


1. Class 3 for PCBway, class 2 for US vendor.
2. Nelco N7000-2HT preferred for flight, but PCBway SH260 is acceptable.

ASSEMBLY COMMENTS:

1. Class 3 preferred

ASSEMBLY NOTES:

1. Stake components specified in BOM with 3M 2216
2. Conformal Coat with Arathane 5750:
Ensure coating does not prevent electrical contact with connectors and mounting holes.

		TECHNOLOGY DEVELOPMENT & ENGINEERING CENTER EAST 11401 HOOVER ROAD, MILAN, OHIO 44846	
TITLE Payload Interface Board			
SIZE B	DWG NO.		REV B
DRAWN BY	CH	ENGINEER	CH
FILE NAME	payload-interface-board.kicad_pcb		KiCad E.D.A. kicad 7.0.1
			2023-06-21 SHEET 1 OF 1